

WHAT IS CLAIMED IS:

1. A method of manufacturing a display device, comprising the steps of:

forming a peeling layer on an element-forming substrate;

forming an insulating layer on said peeling layer;

forming a luminous element on said insulating layer;

bonding a fixed substrate on said luminous element by using a first adhesive;

exposing the entire substrate to a gas containing halogen fluoride after

bonding said fixed substrate to thereby remove said peeling layer; and

bonding a bonding substrate to said insulating layer by using a second

adhesive.

2. A method according to claim 1, wherein polyimide, acrylic, or epoxy resin is

used as said first adhesive.

3. A method according to claim 1, wherein a material used for forming said

bonding substrate is the same as that for forming said fixed substrate.

4. A method of manufacturing a display device, comprising the steps of:

forming a peeling layer on an element-forming substrate;

forming an insulating layer on said peeling layer;

forming a semiconductor element on said insulating layer;

forming a luminous element that is electrically connected to said semiconductor element;

bonding a fixed substrate on said luminous element by using a first adhesive;

exposing the entire substrate to a gas containing halogen fluoride after

~~bonding said fixed substrate to thereby remove said peeling layer; and~~

~~bonding a bonding substrate to said insulating layer by using a second adhesive.~~

5 5. A method according to claim 4, wherein polyimide, acrylic, or epoxy resin is used as said first adhesive.

6. A method according to claim 4, wherein a material used for forming said bonding substrate is the same as that for forming said fixed substrate.

10 7. A method of manufacturing a display device, comprising the steps of:

forming a peeling layer on an element-forming substrate;

forming an insulating layer on said peeling layer;

forming active layers, a gate insulating layer, and gate electrodes over said

15 insulating layer;

forming first openings in said gate insulating layer, said insulating layer, and said peeling layer;

forming a first interlayer insulating layer to cover said gate electrodes;

forming wirings and a pixel electrode on said first interlayer insulating layer;

20 forming second opening in said first interlayer insulating layer, said gate insulating layer, and said insulating layer to thereby expose said peeling layer;

exposing the entire substrate to a gas containing halogen fluoride to thereby remove said peeling layer;

forming a second interlayer insulating layer to cover said wirings and said

25 pixel electrode;

etching said second interlayer insulating layer to thereby expose said pixel electrode;

forming a luminous layer and a cathode on said pixel electrode;

bonding a fixed substrate on said cathode by using a first adhesive;

5 separating said element-forming substrate and said first interlayer insulating layer after bonding said fixed substrate; and

bonding a bonding substrate to said insulating layer by using a second adhesive.

10 8. A method according to claim 7, wherein polyimide, acrylic, or epoxy resin is used as said first adhesive.

9. A method according to claim 7, wherein a material used for forming said bonding substrate is the same as that for forming said fixed substrate.

15 10. A method of manufacturing a display device, comprising the steps of:

forming a peeling layer on an element-forming substrate;

forming an insulating layer on said peeling layer;

forming a first stripe electrode on said insulating layer;

20 bonding a fixed substrate having a second stripe electrode formed thereon on said element-forming substrate by a sealing member;

injecting a liquid crystal between said first stripe electrode and said second stripe electrode;

25 exposing the entire substrate to a gas containing halogen fluoride after injecting the liquid crystal to thereby remove said peeling layer; and

bonding a bonding substrate to said insulating layer by using a second adhesive.

11. A method according to claim 10, wherein polyimide, acrylic, or epoxy resin is used as said first adhesive.

12. A method according to claim 10, wherein a material used for forming said bonding substrate is the same as that for forming said fixed substrate.

13. A method of manufacturing a display device, comprising the steps of:

- forming a peeling layer on an element-forming substrate;
- forming an insulating layer on said peeling layer;
- forming active layers, a gate insulating layer, and gate electrodes on said insulating layer;
- forming a first interlayer insulating layer to cover said gate electrodes;
- forming wirings and a pixel electrode on said first interlayer insulating layer;
- bonding a fixed substrate that is provided with an opposing electrode on said element-forming substrate by a sealing member;
- injecting a liquid crystal between said pixel electrode and said opposing electrode;
- exposing the entire substrate to a gas containing halogen fluoride after injecting the liquid crystal to thereby remove said peeling layer; and
- bonding a bonding substrate to said insulating layer by using a second adhesive.

14. A method according to claim 13, wherein polyimide, acrylic, or epoxy resin is used as said first adhesive.

15. A method according to claim 13, wherein a material used for forming said  
5 bonding substrate is the same as that for forming said fixed substrate.

and as



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